

CSRF Series

Foil on Ceramic Current Sensing Chip Resistor

Stackpole Electronics, Inc.

Resistive Product Solutions

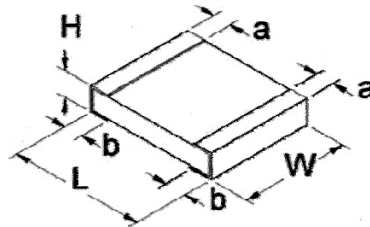
- Features:
- High power rating – up to 2W
 - Low inductance – typically less than 0.2nH
 - Wide resistance range (0.003Ω – 0.100Ω)
 - Current handling up to 40 amps
 - TCR down to ±50 ppm/°C
 - Non-standard resistance values available
 - RoHS compliant / lead-free



| Electrical Specifications | | | | | | |
|---------------------------|-------------|------|-----------------------------|---------------------------------------|--------------------------------|--------------------------------|
| Type / Code | Old Package | Code | Power Rating (Watts) @ 70°C | Resistance Temperature Coefficient(1) | Ohmic Range (Ω) and Tolerance | |
| | | | | | 1% | 5% |
| CSRF0805 | NA | | 0.5W | ±50 ppm/°C | 0.010 - 0.100 | 0.010 - 0.100 |
| CSRF1206 | 1/2 | | 0.5W | ±100 ppm/°C ±50 ppm/°C | 0.005 - 0.010 0.011 - 0.100 | 0.005 - 0.010 0.011 - 0.100 |
| CSRF2010 | 1 | | 1W | ±100 ppm/°C ±50 ppm/°C | 0.003 - 0.010 0.011 - 0.100 | 0.003 - 0.010 0.011 - 0.100 |
| CSRF2512 | 2 | | 2W | ±100 ppm/°C ±50 ppm/°C | 0.003 - 0.010 0.011 - 0.100 | 0.003 - 0.010 0.011 - 0.100 |

(1) Contact factory for TCR parameter for values below 0.01Ω

Please refer to the High Power Resistor Application Note (page 4) for more information on designing and implementing high power resistor types.

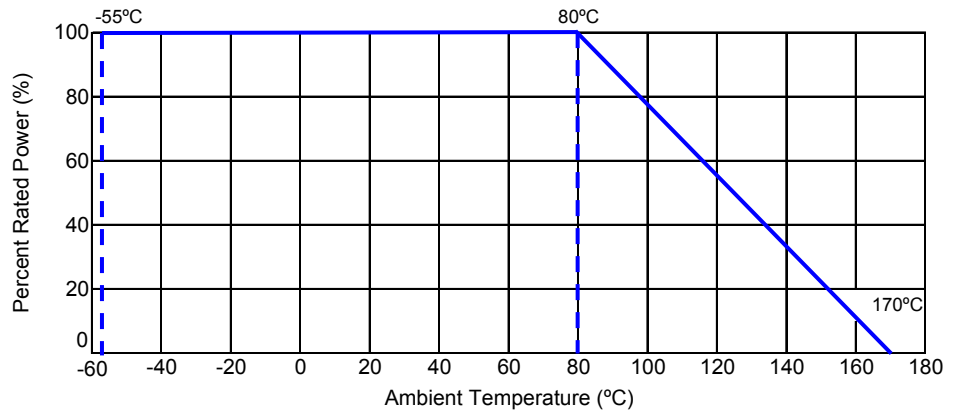


| Mechanical Specifications | | | | | | |
|---------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|--------------|
| Type / Code | L Body Length | W Body Width | H Body Height | a Top Termination | b Bottom Termination | Unit |
| CSRF0805 | 0.079 ± 0.008 2.00 ± 0.20 | 0.049 ± 0.006 1.25 ± 0.15 | 0.024 ± 0.008 0.60 ± 0.20 | 0.016 ± 0.010 0.40 ± 0.25 | 0.020 ± 0.014 0.50 ± 0.35 | inches mm |
| CSRF1206 | 0.126 ± 0.008 3.20 ± 0.20 | 0.063 ± 0.008 1.60 ± 0.20 | 0.030 ± 0.010 0.75 ± 0.25 | 0.020 ± 0.008 0.50 ± 0.20 | 0.022 ± 0.010 0.55 ± 0.25 | inches mm |
| CSRF2010 (3mΩ - 5mΩ) | 0.197 ± 0.010 5.00 ± 0.25 | 0.098 ± 0.008 2.50 ± 0.20 | 0.039 ± 0.006 1.00 ± 0.15 | 0.037 ± 0.006 0.95 ± 0.15 | 0.037 ± 0.006 0.95 ± 0.15 | inches mm |
| CSRF2010 (≥5mΩ) | 0.197 ± 0.010 5.00 ± 0.25 | 0.098 ± 0.008 2.50 ± 0.20 | 0.039 ± 0.006 1.00 ± 0.15 | 0.031 ± 0.006 0.80 ± 0.15 | 0.031 ± 0.006 0.80 ± 0.15 | inches mm |
| CSRF2512 (3mΩ - 5mΩ) | 0.250 ± 0.010 6.35 ± 0.25 | 0.126 ± 0.008 3.20 ± 0.20 | 0.035 ± 0.012 0.90 ± 0.30 | 0.039 ± 0.006 1.00 ± 0.15 | 0.039 ± 0.006 1.00 ± 0.15 | inches mm |
| CSRF2512 (≥6mΩ) | 0.252 ± 0.008 6.40 ± 0.20 | 0.126 ± 0.008 3.20 ± 0.20 | 0.031 ± 0.006 0.80 ± 0.15 | 0.037 ± 0.010 0.95 ± 0.25 | 0.039 ± 0.012 1.00 ± 0.30 | inches mm |

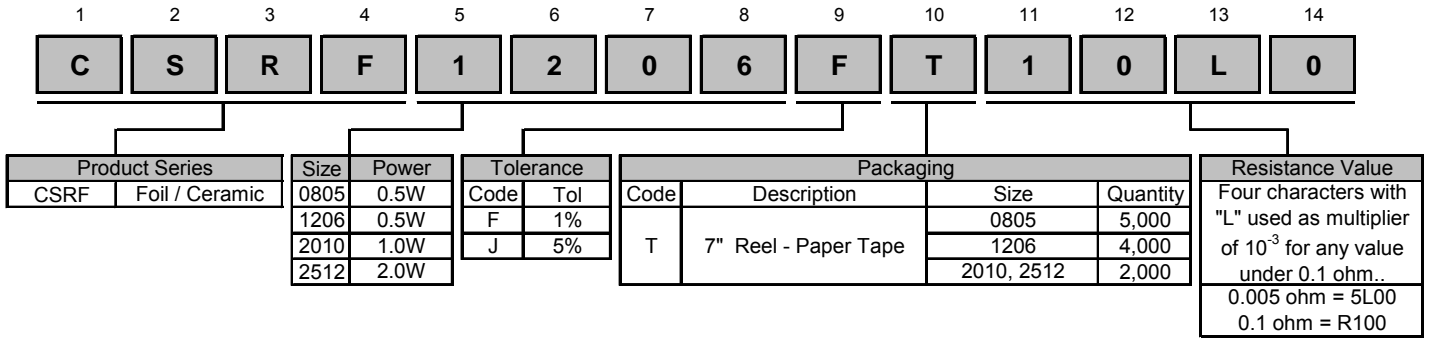
| Performance Characteristics | | | |
|------------------------------|---|----------------------|---------|
| Test | Test Method | Test Specification | Typical |
| Load Life | MIL-STD-202F-Method 108A RCWV at 70°C; 1.5hrs ON; 0.5hrs OFF Total 1024 ± 24hrs | ± 1% | ≤ 0.5% |
| Resistance to Soldering Heat | MIL-STD-202F-Method 210E 260 ± 5°C for 10 ± 1sec | ± 1% | ≤ 0.3% |
| Solderability | MIL-STD-202F-Method 208H 245 ± 5°C for 2 ± 0.5sec | minimum 95% coverage | > 95% |
| Thermal Shock | MIL-STD-202F-Method 107G -55°C to 150°C, 100 cycles | ± 1% | ≤ 0.3% |
| Short Time Overload | JIS-C-5202-5.5 5x rated power for 5 sec | ± 1% | ≤ 0.3% |
| High Temperature Exposure | 125°C: 1000 hous | ± 1% | ≤ 0.2% |
| Moisture Resistance | MIL- STD-202F-Method 106G | ± 1% | ≤ 0.5% |
| Insulation Resistance | MIL-STD-202F-Method 302 Apply 100Vdc for 1 minute | 1MΩ minimum | ≥ 1MΩ |

Operating Temperature Range: -55°C to +170°C

Power Derating Curve:



How to Order



Legacy Part Number (before January 3, 2011):

| SEI Type | | Code | | | Nominal Resistance | Tolerance | Packaging | | | |
|-------------|----------------|------------|---------|------|--------------------|-----------|-----------|----------------------|------|--|
| CSRF | | 1/2 | | | 0.01 | 1% | R | | | |
| Type | Description | Code | Wattage | Size | Tolerance | SEI Types | Pkg Qty | Description | Code | |
| CSRF | Foil / Ceramic | 1/2 | 0.5W | 1206 | 1% | 1/2 | 4,000 | 7" reel - paper tape | R | |
| | | 1 | 1.0W | 2010 | 5% | 1, 2 | 2,000 | | | |
| | | 2 | 2.0W | 2512 | | | | | | |

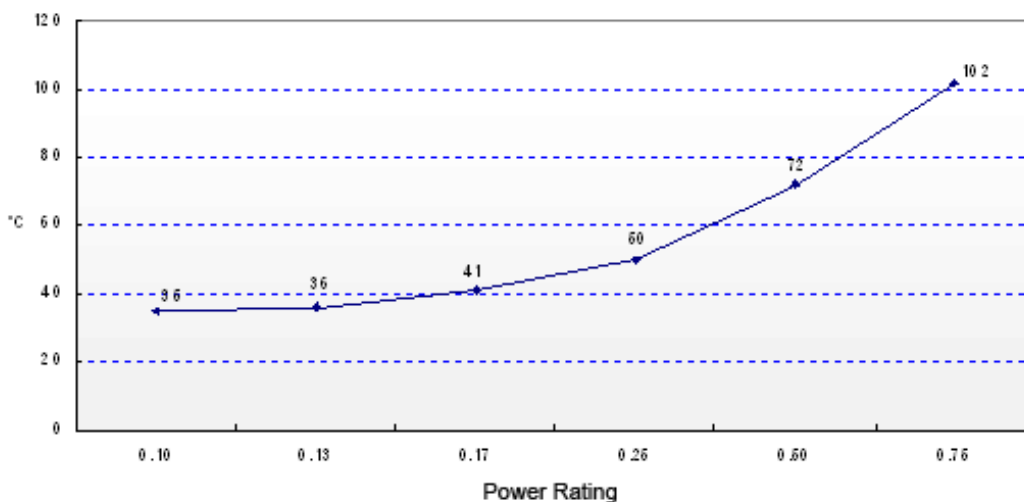
High Power Chip Resistors and Thermal Management

Stackpole has developed several surface mount resistor series in addition to our current sense resistors, which have had higher power ratings than standard resistor chips. This has caused some uncertainty and even confusion by users as to how to reliably use these resistors at the higher power ratings in their designs.

The data sheets for the RHC, RMCP, RNCP, CSR, CSRN, CSRF, CSS, and CSSH state that the rated power assumes an ambient temperature of no more than 100 degrees C for the CSS / CSSH series and 70 degrees C for all other high power resistor series. In addition, IPC and UL best practices dictate that the combined temperature on any resistor due to power dissipated and ambient air shall be no more than 105C. At first glance this wouldn't seem too difficult, however the graph below shows typical heat rise for the CSR 1/2 100 milliohm at full rated power. The heat rise for the RMCP and RNCP would be similar. The RHC with its unique materials, design, and processes would have less heat rise and therefore would be easier to implement for any given customer.

CSR1206 100m Surface Temp Rise

Test equipment:
Chroma Programmable DC Power Supply
YF-162 Type-K thermometer



The 102 degrees C heat rise shown here would indicate there will be additional thermal reduction techniques needed to keep this part under 105C total hot spot temperature if this part is to be used at 0.75 watts of power. However, this same part at the usual power rating for this size would have a heat rise of around 72 degrees C. This additional heat rise may be dealt with using wider conductor traces, larger solder pads and land patterns under the solder mask, heavier copper in the conductors, vias through PCB, air movement, and heat sinks, among many other techniques. Because of the variety of methods customers can use to lower the effective heat rise of the circuit, resistor manufacturers simply specify power ratings with the limitations on ambient air temperature and total hot spot temperatures and leave the details of how to best accomplish this to the design engineers. Design guidelines for products in various market segments can vary widely so it would be unnecessarily constraining for a resistor manufacturer to recommend the use of any of these methods over another.

Note: The final resistance value can be affected by the board layout and assembly process, especially the size of the mounting pads and the amount of solder used. This is especially notable for resistance values ≤ 50 mΩ. This should be taken into account when designing.